applied MICROswiss

High-definition Nozzle plates: Specifications

- Pattern size > 5µm
- Nozzle thickness = 20 - 500µm
- Material: Nickel-Phos12, fully crosslinked Photoepoxy (SU-8)
- Aspect ratio = 5 - 6 (depends on pattern-design)
- EXCLUSIVE: adjustable conical orifices up to 15°
- Manufacturing according to adapted LiGA-process
- Multilevel pattern available (e.g. for integrated microfluidics)
- Alignment-precision level-to-level ≤ 3 µm
- Maximal patterned area = 200 x 200mm
- Parallelism Frontside-to-backside ≤ 10 µm
- Available PVD-coating (e.g. Au, Pt, Pd,...)
- Compatible photoresists for UV-Lithography:
    - AZ positive resists, MicroChem SU-8